

4096x1-BIT DYNAMIC RAM

MK4015 (J/N)

FEATURES

- ☐ Recognized industry standard 16-pin configuration from Mostek
- □ 250ns access time, 380ns cycle
- ☐ Output data latched and valid into next cycle
- □ Low Power: 462mW active (max)38mW standby (max)

- ☐ Improved performance with "gated CAS", "RAS only" refresh, and Read-Modify-Write
- ☐ All inputs are low capacitance and TTL compatible
- ☐ Input latches for addresses, chip select and data in
- ☐ Three-state TTL compatible output

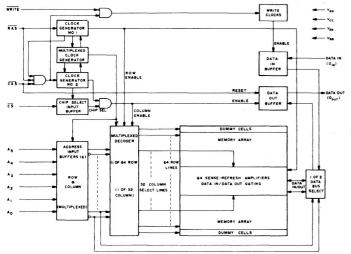
DESCRIPTION

The MK 4015 is a 4096 word by 1 bit MOS random access memory circuit fabricated with MOSTEK's N-channel silicon gate process. This process allows the MK 4015 to be a high performance state-of-the-art memory circuit that is manufacturable in high volume. The MK 4015 employs a single transistor storage cell utilizing a dynamic storage technique and dynamic control circuitry to achieve optimum performance with low power dissipation.

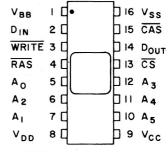
A unique multiplexing and latching technique for the address inputs permits the MK 4015 to be packaged in a standard 16-pin DIP on 0.3 in. centers. This package size provides high system-bit densities and is compatible with widely available automated testing and insertion equipment.

System oriented features include direct interfacing capability with TTL, only 6 very low capacitance address lines to drive, on-chip address and data registers which eliminates the need for interface registers, and two chip select methods to allow the user to determine the appropriate speed/power characteristics of his memory system. The MK 4015 also incorporates several flexible operating modes. In addition to the usual read and write cycles, read-modify write, and RAS-only refresh cycles are available with the MK 4015.

FUNCTIONAL DIAGRAM



PIN CONNECTIONS



PIN NAMES

A₀·A₅ ADDRESS INPUTS COLUMN ADDRESS STROBE cs CHIP SELECT DATA IN DIN POUT DATA OUT ROW ADDRESS STROBE WRITE READ/WRITE INPUT VBB POWER (-5V) Vcc POWER (+5V) VDD POWER (+ 12V) VSS GROUND

RAM

ABSOLUTE MAXIMUM RATINGS*

Voltage on any pin relative to VBB0.5V to +20V
Voltage on VDD, VCC relative to VSS1.0V to +15V
$V_{BB}-V_{SS}$ ($V_{DD}-V_{SS} > 0$)
Operating temperature, TA (Ambient) 0°C to +55°C
Storage temperature (Ambient) (Ceramic)65° C to + 150° C
Storage temperature (Ambient) (Plastic)55°C to + 125°C
Short Circuit Output Current
Power dissipation

*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED DC OPERATING CONDITIONS 4

 $(0^{\circ}C \leq T_{A} \leq 55^{\circ}C)^{-1}$

	PARAMETER	MIN	TYP	MAX	UNITS	NOTES
V_{DD}	Supply Voltage	11.4	12.0	12.6	volts	2
VCC	Supply Voltage	4.5V	5.0	5.5	volts	2,3
VSS	Supply Voltage	0	0	0	volts	2
V _{BB}	Supply Voltage	-4.5	-5.0	-5.5	volts	2
VIHC	Logic 1 Voltage, RAS, CAS, WRITE	3.0	29	7.0	volts	2
VIH	Logic 1 Voltage, all inputs except RAS, CAS, WRITE	3.0		7.0	volts	2
VIL	Logic 0 Voltage, all inputs	-1.0		.65	volts	2

DC ELECTRICAL CHARACTERISTICS 4

 $(0^{\circ}C \leq T_{A} \leq 55^{\circ}C)^{1}$ $(V_{DD} = 12.0V \pm 5\%; V_{CC} = 5.0V \pm 10\%; V_{SS} = 0V; V_{BB} = -5.0V \pm 10\%)$

	PARAMETER	MIN	TYP	MAX	UNITS	NOTES	
I _{DD1}	Average V _{DD} Power Supply Current			35	mA	5	
I _{DD2}	Standby V _{DD} Power Supply Current			3	mA	8	
IDD3	Average VDD Power Supply Current during "RAS only" cycles			25	mA		
ICC	V _{CC} Power Supply Current				mA	6	
I _{BB}	Average VBB Power Supply Current			150	μΑ		
II(L)	Input Leakage Current (any input)			10	μΑ	7	
IO(L)	Output Leakage Current	4.5		10	μΑ	8,9	
VOH	Output Logic 1 Voltage @ IOUT = _5mA	2.4			volts		
VOL	Output Logic 0 Voltage @ IOUT = 3.2mA			0.4	volts		

NOTES

- 1. T_A is specified for operation at frequencies to $t_{RC} \ge t_{RC}$ (min).
- 2. All voltages referenced to $V_{\mbox{SS}}$.
- 3. Output voltage will swing from V_{SS} to V_{CC} when enabled, with no output load. For purposes of maintaining data in standby mode, V_{CC} may be reduced to V_{SS} without affecting refresh operations or data retention. However, the V_{OH} (min) specification is not guaranteed in this mode.
- Several cycles are required after power-up before proper device operation is achieved. Any 8 cycles which perform refresh are adequate for this purpose.
- Current is proportional to cycle rate. IDD1 (max) is measured at the cycle rate specified by t_{RC} (min). See figure 1 for I_{DD1} limits at other cycle rates.
- 6. I_{CC} depends on output loading. During readout of high level data V_{CC} is connected through a low impedance (135 π typ) to Data Out. At all other times I_{CC} consists of leakage currents only.
- 7. All device pins at 0 volts except V_{BB} which is at -5 volts and the pin under test which is at +10 volts.
- Output is disabled (high-impedance) and RAS and CAS are both at a logic 1. Transient stabilization is required prior to measurement of this parameter.
- 10. Effective capacitance is calculated from the equation:
 - $C = \frac{\triangle Q}{\triangle V}$ with $\triangle V = 3$ volts.
- 11. A.C. measurements assume t_T = 5ns.

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ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS⁴,11,17 (0°C \leq TA \leq 55°C)¹ (VDD = 12.0V \pm 5%, VCC = 5.0V \pm 10%, VSS = OV, VBB = -5.0V \pm 10%)

		MK/	MK4015		
	PARAMETER	MIN	MAX	Units	Notes
^t RC	Random read or write cycle time	380		ns	
RWC	Read write cycle time	395		ns	
tRMW	Read modify write cycle time	470		ns	
^t RAC	Access time from row address strobe		250	ns	13,15
^t CAC	Access time from column address strobe		165	ns	14,15
^t OFF	Output buffer turn-off delay		60	ns	
tRP	Row address strobe precharge time	120		ns	
^t RAS	Row address strobe pulse width	250	4000	ns	
^t RSH	Row address strobe hold time	165		ns	
tCAS	Column address strobe pulse width	165	4000	ns	
tCSH	Column address strobe hold time	250		ns	
^t RCD	Row to column strobe delay	35	85	ns	16
tASR	Row address set-up time	0		ns	
^t RAH	Row address hold time	35		ns	
tASC	Column address set-up time	0		ns	
tCAH	Column address hold time	75		ns	
tAR	Column address hold time referenced to RAS	160		ns	
tcsc	Chip select set-up time	0		ns	
^t CH	Chip select hold time	75		ns	
^t CHR	Chip select hold time referenced to RAS	160		ns	
tŢ	Transition time (rise and fall)	3	50	ns	17
tRCS	Read command set-up time	0		ns	
^t RCH	Read command hold time	0		ns	
†WCH	Write command hold time	75		ns	
tWCR	Write command hold time referenced to RAS	160		ns	
tWP	Write command pulse width	75		ns	
^t RWL	Write command to row strobe lead time	100	7	ns	1
t _{CWL}	Write command to column strobe lead time	100		ns	
tDS	Data in set-up time	0		ns	18
^t DH	Data in hold time	75		ns	18
tDHR	Data in hold time referenced to RAS	160		ns	1
tCRP	Column to row strobe precharge time	0		ns	
tRFSH	Refresh period		1	ms	1
twcs	Write command set-up time	0		ns	19
tCWD	CAS to WRITE delay	90		ns	19
tRWD	RAS to WRITE delay	175		ns	19
tDOH	Data out hold time	4		μS	í

Notes Continued

- Assumes that t_{RCD} ≤ t_{RCD} (max).
- 14. Assumes that $t_{RCD} \geqslant t_{RCD}$ (max).
- 15. Measured with a load circuit equivalent to 2 TTL loads and 100pF
- 16. Operation within the t_{RCD} (max) limit insures that t_{RAC} (max) can be met. t_{RCD} (max) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC}.
- V_{IHC} (min) or V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IHC} or V_{IH} and V_{IL}.
- These parameters are referenced to CAS leading edge in random write cycles and to WRITE leading edge in delayed write or readmodify write cycles
- 19. tWCS, tCWD, and tRWD are restrictive operating parameters in a read/write or read/modify/write cycle only. If twcs ≥ tWCS (min), the cycle is an early write cycle and Data Out will contain the data written into the selected cell. If tCWD ≥ tCWD (min) and tRWD ≥ tRWD (min), the cycle is a read-write cycle and Data Out will contain data read from the selected cell. If neither of the above sets of conditions is satisfied, the condition of Data Out (at access time) is indeterminate.

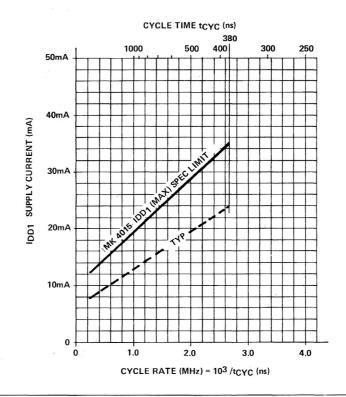
AC ELECTRICAL CHARACTERISTICS

 $(0^{\circ}\text{C} \leq \text{T}_{A} \leq 55^{\circ}\text{C}) \text{ (V}_{DD} = 12\text{V} \pm 5\%; \text{V}_{SS} = 0\text{V}; \text{V}_{BB} = -5.0\text{V} \pm 10\%)$

	PARAMETER	TYP	MAX	UNITS	NOTES
C 11	Input Capacitance (A ₀ -A ₅), D _{IN} , $\overline{\text{CS}}$	4	5	pF	10
C ₁₂	Input Capacitance RAS, CAS, WRITE	8	10	pF	10
C ₀	Output Capacitance (DOUT)	5	7	pF	8,10

MAXIMUM IDD1 vs. CYCLE RATE

Figure 1



SUPPLEMENT - To be used in conjunction with MK4027(P/J/N)-1/2/3 data sheet.